

RESPONSE TO OFFICE ACTION**Serial No. 09/921,588****Page 2 of 5****IN THE CLAIMS:**

1-22. (Cancelled)

23. (Previously Presented) A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

flowing polishing fluid onto a first portion of a rotating polishing pad at a first rate;
and

flowing polishing fluid of equal concentration on a second portion of the polishing pad at a second rate that is different than the first rate, wherein the polishing fluid disposed on the first portion has a greater volume as it interfaces with a substrate being polished than the polishing fluid disposed on the second portion.

24. (Original) The method of claim 23, wherein the first rate is independently controllable relative the second rate.

25. (Previously Presented) The method of claim 23 further comprising:

flowing the polishing fluid on the pad at one or more locations between the first portion and the second portion.

26. (Original) The method of claim 23, wherein the step of flowing the polishing fluid at a first rate further comprises:

adjusting the flow rate during polishing.

27. (Original) The method of claim 26, wherein the step of adjusting further comprises:

adjusting the flow rate in response to a polishing metric.

30-39. (Cancelled)

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